

AUGUST, 2024



Investor Presentation

Jefferies Semiconductor, IT Hardware & Communication Technology Conference

August 28, 2024

Disclaimer

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec SE and its subsidiaries and associates.

Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec SE. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements.

SUSS MicroTec SE does not intend or accept any obligation to publish updates of these forward-looking statements.



SUSS MicroTec at a glance



- Hidden champion headquartered in Germany with 75 years track record of innovation and growth
- Key technology provider for semiconductor frontend and advanced backend industry
- Global customer base with largest share of business in Asia
- Strategic partner for global semiconductor IDMs and foundries
- Innovator with relevant network to research institutes and universities
- 2025 Target: € 400 million revenue and >15% EBIT margin

304.3
in € million

Sales
2023

420.5
in € million

Order intake
2023

9.1%

EBIT margin
2023

Management Board of SUSS MicroTec SE



CFO

Dr. Cornelia Ballwiesser

- Finance and Controlling
- Legal and Compliance
- Internal Audit
- Investor Relations
- IT
- ESG



CEO

Burkhardt Frick

- Sales and Service
- Strategy
- HR
- Business Units:
Advanced Backend Solutions,
Photomask Solutions



COO

Dr. Thomas Rohe

- R&D
- Purchasing
- Production
- Logistics
- Quality Management
- Product Center
- Facility Management

Our corporate vision defines our strategies

SUSS MicroTec Vision

**Leader in enabling innovative
advanced backend & photomask
solutions.**

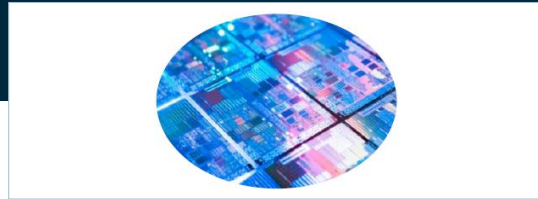
Our world are the semiconductor frontend and backend process steps

Wafer fabrication



Front-end-of-line

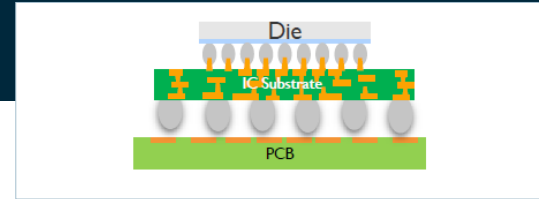
Wafer process



- Deposition/coating
- Cleaning
- **Patterning/lithography**¹
- Etching
- Implantation
- Annealing
- **Permanent bonding**
- **Temporary bonding**
- CMP polishing

From middle-of-line to back-end-of-line

Advanced packaging



- Deposition/coating
- Cleaning
- **Patterning/lithography**
- Etching
- Annealing
- CMP polishing
- **Permanent bonding**
- **Temporary bonding**
- **Wafer-level packaging**
- Wafer dicing
- Panel-level packaging

Final packaging



- Mounting
- Wire bonding
- Molding encapsulation
- Trim & forming

¹ Only related to Photomask processing

Source: Yole, Lithography and Bonding Equipment for More than Moore 2022

Advanced Backend Solutions is the core asset in our product portfolio



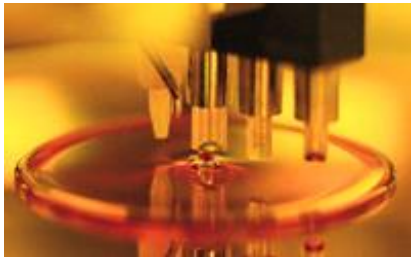
Frontend

Segments Photomask Solutions



Advanced Backend

Advanced Backend Solutions



Products

Photomask Equipment



MaskTrack X

Imaging

Mask Aligner
MA200/300





Projection Scanner
DSC300

Coating



ACS300

Bonding

XBC300

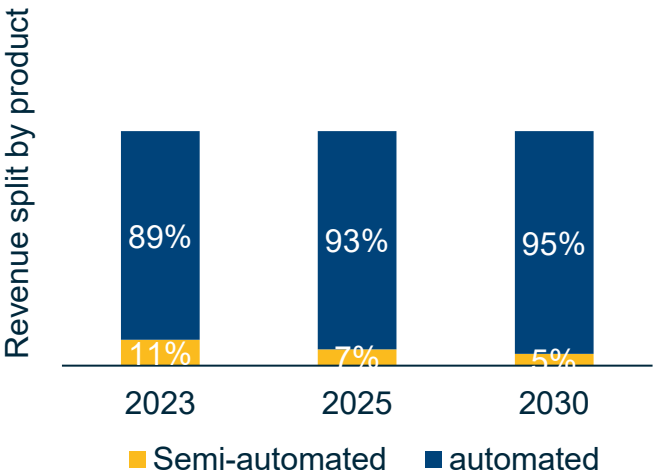
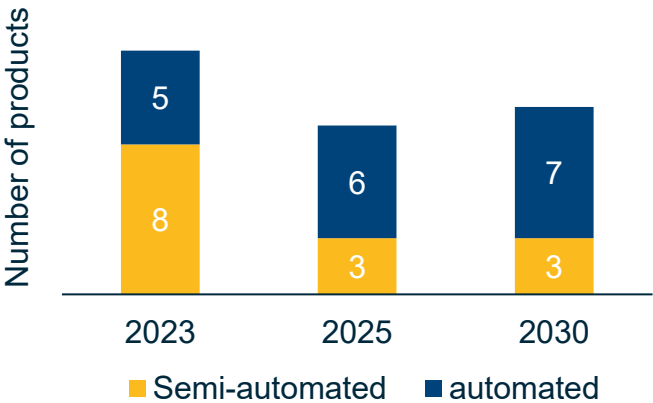




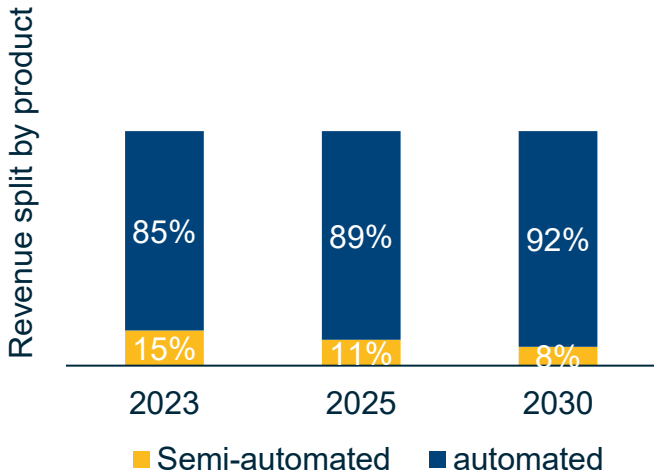
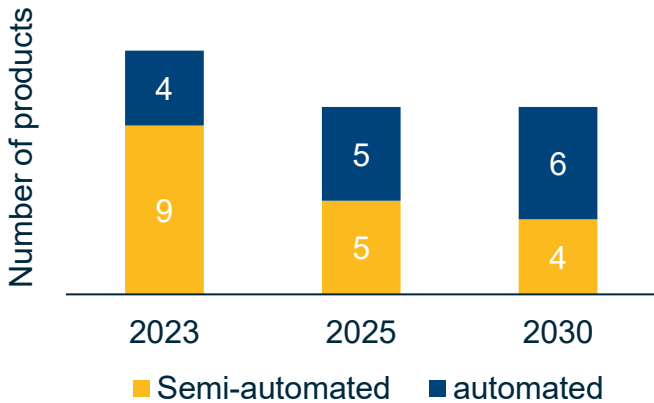
XB8

Focus on high-volume manufacturing markets while semi-automated tools will be phased-out during next years in Advanced Backend Solutions business unit

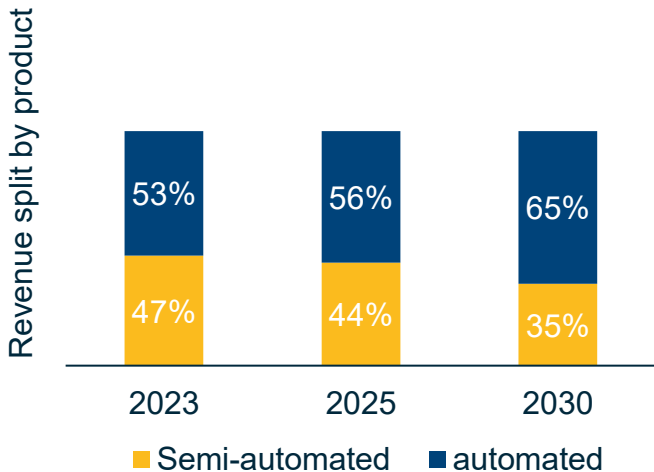
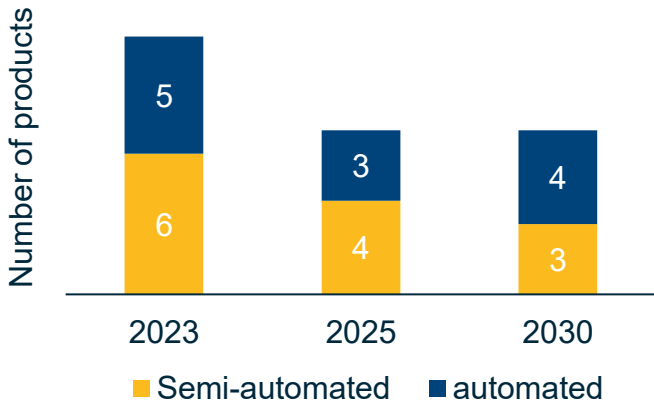
Bonding Systems



Coating Systems



Imaging Systems




Full range of bonding solutions by SUSS



Temporary Bonding

Temporary Bonding
XBS300



Permanent Bonding

Bonding (200mm)
XBS200



Hybrid Bonding

W2W (up to 200mm)
XBS200



W2W (up to 300mm)
XBS300 W2W



De-bonding / Cleaning
XBC300 Gen2



D2W & W2W
XBC300 Gen2 D2W/W2W



D2W
XBC300 Gen2 D2W



Mech. De-bonding (semi-auto)
DB12T



High-force Bonding (semi-auto)
SB8 Gen2 /XB8



We have built up additional temporary bonding capacity in Taiwan



- We added 50+ people in Hsinchu in order increase manufacturing capacity for temporary bonders
- First temporary bonder 'made in Taiwan' has been completed at the beginning of March 2024
- Full capacity available as of Q3-2024
- Total manufacturing capacity for temporary bonding equipment (bonder, debonder and cleaner) in Sternenfels and Hsinchu allows us to generate yearly sales of ~ €150 million.

SUSS hybrid bonding solutions – understanding customer's needs

Wafer-to-wafer HB XBS300 W2W

Product launch: 10/2022
Target customers: HVM



Die-to-wafer/wafer-to-wafer HB XBC300 Gen2 D2W/W2W

Product launch: 05/2024
Target customers: research institutes,
R&D teams of HVM



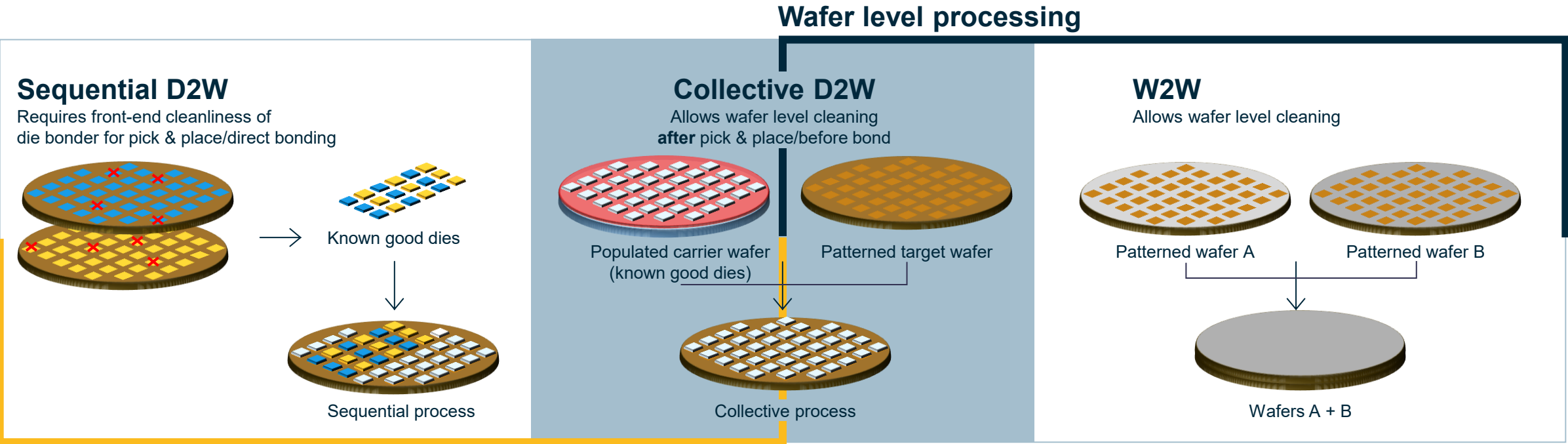
Die-to-wafer HB XBC300 Gen2 D2W

Product launch: Q4/2024
Target customers: HVM



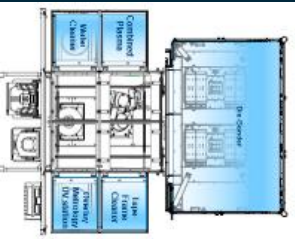
We optimize our product solutions to serve our customer's device and manufacturing needs.

SUSS MicroTec's solutions for different hybrid bonding processing schemes



Single die processing

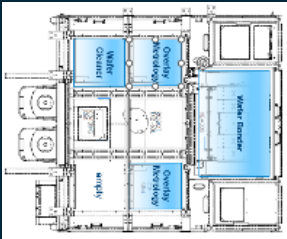
Surface Preparation (SP) & D2W



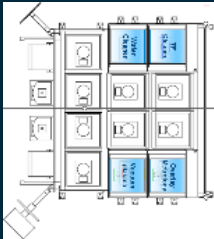
SP & D2W/W2W



SP & W2W



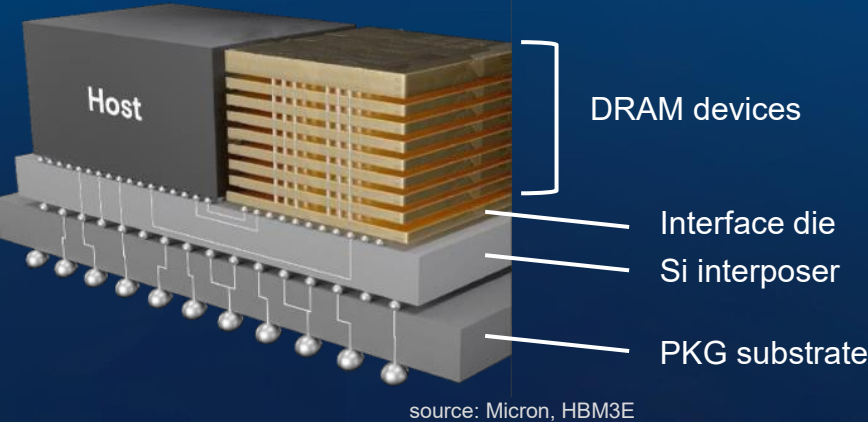
SP only



Overlay only



HBM roadmap enables SUSS to grow in existing and new markets



| | HBM3E | HBM4 | HBM4E | HBM5 |
|-------------------------------|-------|------|--------------|--------------|
| Expected SOP | 2024 | 2025 | 2026 or 2027 | 2027 or 2028 |
| # of DRAM layer acc. to JEDEC | 8/12 | 12 | 16 | 16/20 |
| Bonding type in DRAM stack | TCB | TCB | TCB or HB | HB |
| Thinning of DRAM devices | TBDB | TBDB | TBDB | TBDB |

Relevance for SUSS:

TBDB remains a crucial process for thinning of DRAM devices used in HBM cube

Growth of existing SUSS TBDB business in line with general HBM market growth

Increase of layer number in HBM cube triggers more TBDB capacity for thinning of DRAM devices

Additional growth of SUSS TBDB business in line with higher layer in HBM cube

Hybrid bonding will gradually replace Thermal Compression bonding for stacking of DRAM devices

Expansion into this market offers new growth opportunities with SUSS HB solutions

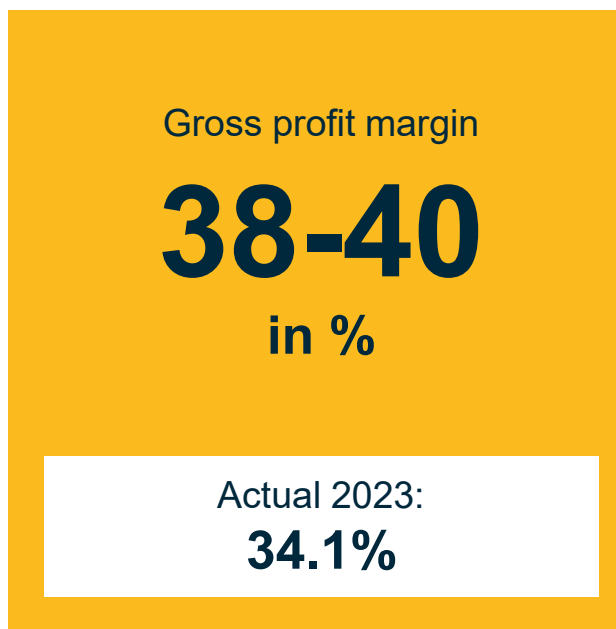
TCB: Thermal compression bonding, HB: hybrid bonding, TBDB: Temporary bonding & de-bonding

Based on the strong H1 performance, we have raised our forecast for 2024

Guidance 2024 (as of July 18, 2024)



Initial guidance:
Sales of € 340-370 million



Initial guidance:
Gross profit margin of 35-38%



Initial guidance:
EBIT margin of 10-12%

Strong execution in H1 2024, leading to top-line growth and margin expansion

Financial Results

H1 2024*

192.2
in € million

Order intake
H1 2024

+7.9% YoY

192.8
in € million

Sales
H1 2024

+45.6% YoY

39.8
in %

Gross profit margin
H1 2024

+4.2pp YoY

15.6
in %

EBIT margin
H1 2024

+6.9pp YoY

*Adjusted for divested MicroOptics business

Key CEO messages



- Execution of well-filled order book was very successful in H1 2024 with growth of 45.6% and increased gross profit margin and EBIT margin.
- We are confident that our strong performance will continue in H2 2024. As a result, we have raised our guidance for all three financial KPIs.
- Based on the high order book level of €450 million, we will continue to push ahead with the expansion of flexible production capacity and measures to increase operational efficiency.

SUSS is committed to be a strong partner for further growth and we are working hard to further accelerate our ability to deliver from our manufacturing facilities in Germany and Taiwan.

Strong growth and improving profitability in H1 2024

| In € million | H1 2024 | H1 2023 | Change |
|--|--------------|--------------|-----------------|
| Order intake | 192.2 | 178.2 | + 7.9% |
| Order book as of June 30 | 450.0 | 381.5 | + 18.0% |
| Sales | 192.8 | 132.4 | + 45.6% |
| Gross profit | 76.8 | 47.1 | + 63.1% |
| Gross profit margin | 39.8% | 35.6% | + 4.2pp |
| EBIT | 30.1 | 11.5 | + 161.7% |
| EBIT margin | 15.6% | 8.7% | + 6.9pp |
| Earnings after taxes (continuing operations) | 22.5 | 9.4 | +139.4% |
| Net profit* | 80.8 | 6.2 | -- |
| Earnings per share, basic (in €), continuing operations | 1.18 | 0.49 | + 140.8% |
| Earnings per share, basic (in €)* | 4.23 | 0.32 | -- |
| Net cash | 121.0 | 40.2 | + 201.0% |
| Free cash flow (continuing operations) | 22.6 | 5.1 | + 443.1% |
| Free cash flow total* | 93.3 | 1.1 | -- |
| Employees as of June 30 | 1,310 | 1,105 | + 18.6% |

*Not adjusted for divested MicroOptics business

- Order intake grew year-on-year in the first six months, Q2 2024 slightly below Q1 2024 but above the level of Q2 2023.
- Favorable product mix and a disproportionately low increase in OPEX resulted in a positive development of gross profit margin and EBIT margin.
- Net profit includes extraordinary income from MicroOptics sale (€ 58.8 million); earnings from continuing operations also significantly higher.
- Improved free cash flow from continuing operations demonstrates ability to convert higher volume and margin improvements into cash.
- Expansion of headcount mainly driven by new employees for production in Germany and Taiwan and R&D.

Division Overview H1 2024

Advanced Backend Solutions

| in € million | H1 2024 | H1 2023 |
|----------------------------|---------|---------|
| Order intake | 130.4 | 93.5 |
| Order book | 280.4 | 200.2 |
| Sales | 136.0 | 97.8 |
| Gross profit | 57.5 | 36.5 |
| Gross profit margin | 42.3% | 37.3% |
| EBIT | 21.3 | 9.1 |
| EBIT margin | 15.7% | 9.4% |

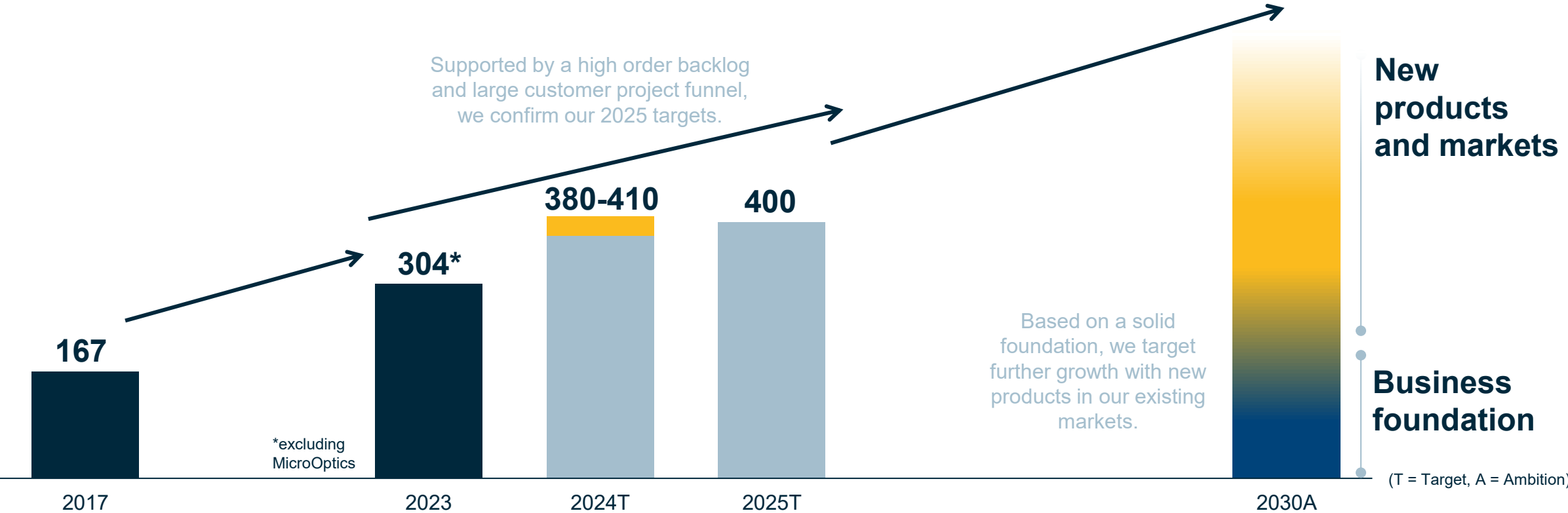
Photomask Solutions

| in € million | H1 2024 | H1 2023 |
|----------------------------|---------|---------|
| Order intake | 61.8 | 84.7 |
| Order book | 169.9 | 181.4 |
| Sales | 56.8 | 34.5 |
| Gross profit | 19.6 | 10.7 |
| Gross profit margin | 34.5% | 30.9% |
| EBIT | 11.0 | 4.4 |
| EBIT margin | 19.4% | 12.6% |

- Continued order intake momentum from our Bonder product line, especially for temporary bonding equipment; order from US-based technology partner BRIDG for our D2W/W2W hybrid bonding platform
- Significant sales growth, mainly driven by execution of bonder orders received in H2 2023
- Unchanged softness in Imaging and Coating product line
- Gross profit margin and EBIT margin increase as a result of favorable product mix and under-proportional increase in OPEX

- Order intake on a lower level than in H1 2023, but order book still exceeds annual production capacity
- Strong order book level of ~€170 million provides high visibility through mid-2025
- Increased profitability due to a very favorable product and customer mix
- Small number of systems sold can result in greater volatility due to changes in product and customer mix

Based on our business foundation we see further potential beyond



Major growth drivers 2023

- Converting high order backlog in Photomask Solutions and Bonder business into sales growth

Major growth drivers 2024/2025

- Bonding (especially with regard to AI-driven demand for temporary bonders)
- Photomask Solutions

Major growth drivers 2030

- General expected market growth in our core businesses (lithography, bonding, photomask)
- Hybrid Bonding
- Wafer Cleaning

Investor Relations Information

Contact

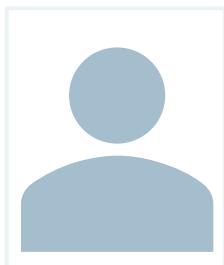


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Financial Calendar 2024



March 27
Annual Report 2023



May 8
Q1 Report 2024



June 11
Annual General Meeting 2024



August 7
Half Year Report 2024



November 7
Nine Months Report 2024